

Youngwoo Kim

List of Publications by Year in descending order

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citing authors

#	ARTICLE	IF	CITATIONS
1	An Overhead-Reduced Key Coding Technique for High-Speed Serial Interface. IEEE Access, 2022, 10, 21187-21192.	4.2	0
2	Target Capacity Filter Pruning Method for Optimized Inference Time Based on YOLOv5 in Embedded Systems. IEEE Access, 2022, 10, 70840-70849.	4.2	3
3	A Resource Efficient Integer-Arithmetic-Only FPGA-Based CNN Accelerator for Real-Time Facial Emotion Recognition. IEEE Access, 2021, 9, 104367-104381.	4.2	23
4	An Energy-Efficient Deep Neural Network Training Processor with Bit-Slice-Level Reconfigurability and Sparsity Exploitation. , 2021, , .		0
5	Robust detection of small and dense objects in images from autonomous aerial vehicles. Electronics Letters, 2021, 57, 611-613.	1.0	3
6	A No-Reference CNN-Based Super-Resolution Method for KOMPSAT-3 Using Adaptive Image Quality Modification. Remote Sensing, 2021, 13, 3301.	4.0	2
7	HNPU: An Adaptive DNN Training Processor Utilizing Stochastic Dynamic Fixed-Point and Active Bit-Precision Searching. IEEE Journal of Solid-State Circuits, 2021, 56, 2858-2869.	5.4	36
8	S3: A Spectral-Spatial Structure Loss for Pan-Sharpening Networks. IEEE Geoscience and Remote Sensing Letters, 2020, 17, 829-833.	3.1	15
9	Signal Integrity Design and Analysis of 3-D X-Point Memory Considering Crosstalk and IR Drop for Higher Performance Computing. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 858-869.	2.5	11
10	A 0.22â€“0.89 mW Low-Power and Highly-Secure Always-On Face Recognition Processor With Adversarial Attack Prevention. IEEE Transactions on Circuits and Systems II: Express Briefs, 2020, 67, 846-850.	3.0	10
11	A CNN-Based Multi-scale Super-Resolution Architecture on FPGA for 4K/8K UHD Applications. Lecture Notes in Computer Science, 2020, , 739-744.	1.3	2
12	A Real-Time Convolutional Neural Network for Super-Resolution on FPGA With Applications to 4K UHD 60 fps Video Services. IEEE Transactions on Circuits and Systems for Video Technology, 2019, 29, 2521-2534.	8.3	59
13	An Energy-Efficient Deep Reinforcement Learning Accelerator With Transposable PE Array and Experience Compression. IEEE Solid-State Circuits Letters, 2019, 2, 228-231.	2.0	5
14	Design and Measurement of a Novel On-Interposer Active Power Distribution Network for Efficient Simultaneous Switching Noise Suppression in 2.5-D/3-D IC. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 317-328.	2.5	12
15	Fast and Accurate Power Distribution Network Modeling of a Silicon Interposer for 2.5-D/3-D ICs With Multiaarray TSVs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1835-1846.	2.5	19
16	Signal Integrity Design and Analysis of Silicon Interposer for GPU-Memory Channels in High-Bandwidth Memory Interface. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1658-1671.	2.5	40
17	EMI Reduction Methods in Wireless Power Transfer System for Drone Electrical Charger Using Tightly Coupled Three-Phase Resonant Magnetic Field. IEEE Transactions on Industrial Electronics, 2018, 65, 6839-6849.	7.9	104
18	2X Super-Resolution Hardware Using Edge-Orientation-Based Linear Mapping for Real-Time 4K UHD 60 fps Video Applications. IEEE Transactions on Circuits and Systems II: Express Briefs, 2018, 65, 1274-1278.	3.0	18

#	ARTICLE	IF	CITATIONS
19	Eye-diagram estimation with stochastic model for 8B/10B encoded high-speed channel. , 2018, , .		2
20	Modeling, Measurement, and Analysis of Audio Frequency Ground Integrity for a TDMA Smartphone System. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 519-530.	2.5	4
21	Glass Interposer Electromagnetic Bandgap Structure for Efficient Suppression of Power/Ground Noise Coupling. IEEE Transactions on Electromagnetic Compatibility, 2017, 59, 940-951.	2.2	13
22	Signal and power integrity (SI/PI) analysis of heterogeneous integration using embedded multi-die interconnect bridge (EMIB) technology for high bandwidth memory (HBM). , 2017, , .		4
23	Glass-Interposer Electromagnetic Bandgap Structure With Defected Ground Plane for Broadband Suppression of Power/Ground Noise Coupling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1493-1505.	2.5	9
24	analysis of power inverter parasitic inductances effect on switching characteristics for accurate electromagnetic interference (EMI) estimation. , 2017, , .		3
25	Eye-Diagram Estimation Methods for Voltage-and Probability-Dependent PAM-4 Signal on Stacked Through-Silicon Vias (TSVs). , 2017, , .		4
26	Design and Analysis of Power Distribution Network (PDN) for High Bandwidth Memory (HBM) Interposer in 2.5D Terabyte/s Bandwidth Graphics Module. , 2016, , .		24
27	Power distribution network (PDN) design and analysis of a single and double-sided high bandwidth memory (HBM) interposer for 2.5D Terabyte/s bandwidth system. , 2016, , .		13
28	Electromagnetic Bandgap Design for Power Distribution Network Noise Isolation in the Glass Interposer. , 2016, , .		2
29	Measurement and Analysis of Glass Interposer Power Distribution Network Resonance Effects on a High-Speed Through Glass Via Channel. IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 1747-1759.	2.2	18
30	Design of an On-Interposer Passive Equalizer for High Bandwidth Memory (HBM) with 30Gbps Data Transmission. , 2016, , .		1
31	Mobile AP GPU power distribution network simulation and analysis based on chip power model. , 2016, , .		3
32	Design optimization of high bandwidth memory (HBM) interposer considering signal integrity. , 2015, , .		21
33	Electrical characteristics analysis and comparison between through silicon via(TSV) and through glass via(TGV). , 2015, , .		7
34	Design of an on-interposer passive equalizer embedded on a ground plane for 30Gbps serial data transmission. , 2015, , .		1
35	Power distribution network design and optimization based on frequency dependent target impedance. , 2015, , .		13
36	Analysis and optimization of a power distribution network in 2.5D IC with glass interposer. , 2014, , .		3

#	ARTICLE	IF	CITATIONS
37	Analysis of Power Distribution Network in glass, silicon interposer and PCB. , 2014, , .		13
38	Analysis of glass interposer PDN and proposal of PDN resonance suppression methods. , 2013, , .		8
39	Radio resource management in multiple-chip-rate DS/CDMA systems supporting multiclass services. IEEE Transactions on Vehicular Technology, 2001, 50, 723-736.	6.3	10